

ABSTRACT OF THE DISCLOSURE

A dicing/die-bonding film including a pressure-sensitive adhesive layer (2) on a supporting base material (1) and a
die-bonding adhesive layer (3) on the pressure-sensitive adhesive
layer (2), wherein a releasability in an interface between the
pressure-sensitive adhesive layer (2) and the die-bonding adhesive
layer (3) is different between an interface (A) corresponding to a
work-attaching region (3a) in the die-bonding adhesive layer (3) and
an interface (B) corresponding to a part or a whole of the other
region (3b), and the releasability of the interface (A) is higher than
the releasability of the interface (B). The dicing/die-bonding film is
excellent in balance between retention in dicing a work and
releasability in releasing its diced chipped work together with the
die-bonding adhesive layer.